



(51) International Patent Classification:

B24B 37/24 (2012.01) **B24B 49/10** (2006.01)
B24B 49/04 (2006.01)

(21) International Application Number:

PCT/US2011/053678

(22) International Filing Date:

28 September 2011 (28.09.2011)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

12/895,529	30 September 2010 (30.09.2010)	US
12/895,479	30 September 2010 (30.09.2010)	US
12/895,465	30 September 2010 (30.09.2010)	US

(71) Applicant (for all designated States except US): **NEX-PLANAR CORPORATION** [US/US]; 7425 Nw Evergreen Parkway, Suite 150, Hillsboro, OR 97124 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **WILLIAM, Allison, C.** [US/US]; 4243 NW Chaparral Terrace, Beaverton, OR 97006 (US). **SCOTT, Diane** [US/US]; 3140 NE Bryce Street, Portland, OR 97212 (US). **HUANG, Ping** [CN/US]; 7365 Howard Lane, Apt. 204, Eden Prairie, MN 55346 (US). **FRENTZEL, Richard** [US/US]; 31900 Serranto Drive, Murrieta, CA 92563 (US). **SIMPSON, Alexander, William** [GB/US]; 2515 Nw Overlook Drive, Apt.323, Hillsboro, OR 97124 (US).

(74) Agents: **VINCENT, Lester, J.** et al.; **BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP**, 1279 Oakmead Parkway, Sunnyvale, CA 94085-4040 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report (Art. 21(3))
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))

(88) Date of publication of the international search report:

24 May 2012

(54) Title: POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION

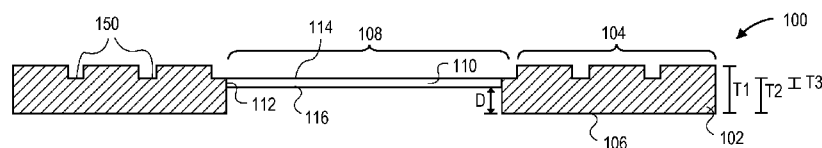


FIG. 1A

(57) Abstract: Polishing pads for polishing semiconductor substrates using eddy current end-point detection are described. Methods of fabricating polishing pads for polishing semiconductor substrates using eddy current end-point detection are also described.